

B. Specification

Please amend the paragraph at page 33, line 4, to page 34, line 15, as follows:

--On the other hand, as the hardening composition having a negative type photosensitive property as a nozzle forming material, those having the properties as a member for forming a liquid flow path wall or a discharge port, and the resistance as the liquid flow path forming mold material with respect to the process of dissolving and removing the positive type resist, or the like may be used, and a photo setting composition including a cationically polymerizable chemical compound, cationic photopolymerization initiator, and a cationic polymerization inhibitor can be used. As the cationically polymerizable chemical compound to be included in the photo setting composition, those capable of having the compounds coupled with each other, utilizing the cationic addition polymerization reaction can be used. For example, as shown in the Japanese Patent Application Laid-Open No. 3-143307 (corresponding to U.S. Patent No. 3,143,3075,478,606), epoxy compounds, which are solid at ordinary temperature can be preferably used. For example, those having at least about 900 molecular weight out of the reaction products of a bisphenol A and an epichlorohydrin, a reaction product of a phenol A including a bromoth, and an epichlorohydrin, a phenol novolak, a reaction products of an o-cresol novolak and epichlorohydrin, the polyfunctional epoxy resins having an oxycyclohexane skeleton disclosed in Japanese Patent Application Laid-Open Nos. S60-161973, S62-221121, S64-9216, and H02-140219, or the like can be presented. They can

be used by one kind or two or more kinds. Moreover, according to these epoxy compounds, a compound preferably having a 2,000 or less epoxy equivalent, and more preferably having a 1,000 or less epoxy equivalent can be used preferably. If the epoxy equivalent is more than 2,000, the cross linking density is lowered at the time of the hardening reaction so that Tg or the thermal deformation temperature of the hardened product is lowered, or a problem may be generated in terms of the adhesion property and the ink resistance property.--

Please amend the paragraph at page 50, lines 4-26, as follows:

--Then, as shown in FIG. 4D, the upper layer resist layer 33 is developed.

As the developing solution, a solvent capable of at least dissolving the exposing part and hardly dissolving the unexposed part can be used. As a result of the elaborate discussion of the present inventors, it was found out that a developing solution containing a glycol ether having 6 or more carbon atoms to be mixed with water by an optional ratio, a nitrogen containing basic organic solvent and water can be used particularly preferably. As the glycol ether, an ethylene glycol monobutyl ether and/or diethylene glycol monobutyl ether, and as the nitrogen containing basic organic solvent, an ethanolamine and/or ~~a morpholin morpholine can be used are~~ particularly preferably preferred. For example, as a developing solution for the PMMA (polymethyl methacrylate) used as a resist in the X ray lithography, a developing solution having the composition disclosed in Japanese Patent Application Laid-Open No. H03-10089 (corresponding to U.S. Patent No. 4,393,129) can be used

preferably also in the present invention. As to the composition ratio of each of the above-mentioned components, for example, a developing solution containing:--